

SURFACE MOUNT DISPLAY

KPCA03-102 SUPER BRIGHT GREEN

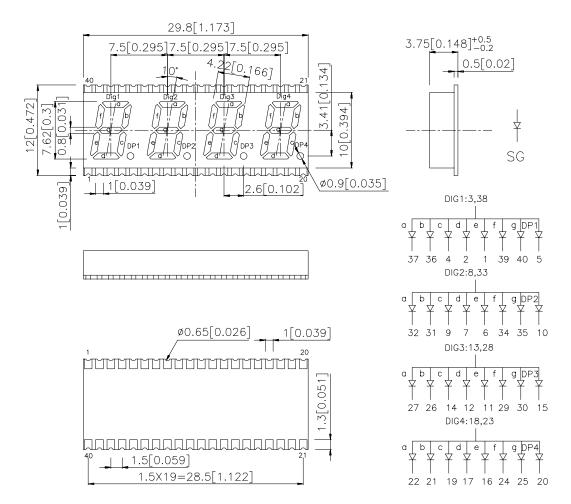
Features

- •0.3 INCH DIGIT HEIGHT.
- •LOW CURRENT OPERATION.
- •EXCELLENT CHARACTER APPEARANCE.
- •I.C. COMPATIBLE.
- •MECHANICALLY RUGGED.
- •GRAY FACE, WHITE SEGMENT.
- •PACKAGE: 800PCS/REEL.

Description

The Super Bright Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions& Internal Circuit Diagram



Notes

- 1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 2. Specifications are subject to change whitout notice.

SPEC NO: DSAB4376 APPROVED: J. Lu REV NO: V.3 CHECKED :Joe Lee DATE: NOV/16/2002 DRAWN: F.Y.YUAN PAGE: 1 OF 5



Selection Guide

Part No.	Dice	Lens Type	lv (ucd) @ 10 mA		Description	
			Min.	Тур.		
KPCA03-102	SUPER BRIGHT GREEN (GaP)	WHITE DIFFUSED	1200	5600	Common Anode,Rt. Hand Decimal	

Electrical / Optical Characteristics at T_A=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Green	565		nm	IF=20mA
λD	Dominate Wavelength	Super Bright Green	568		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Green	30		nm	IF=20mA
С	Capacitance	Super Bright Green	15		pF	VF=0V;f=1MHz
VF	Forward Voltage	Super Bright Green	2.2	2.5	V	IF=20mA
IR	Reverse Current	Super Bright Green		10	uA	VR = 5V

Absolute Maximum Ratings at T_A=25°C

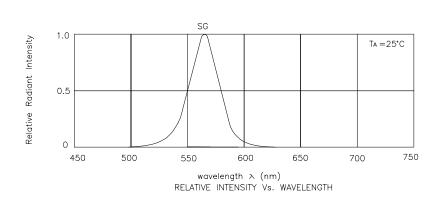
Parameter	Super Bright Green	Units
Power dissipation	105	mW
DC Forward Current	25	mA
Peak Forward Current [1]	140	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

Note:

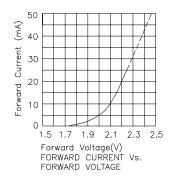
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

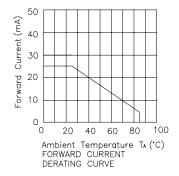
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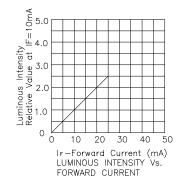


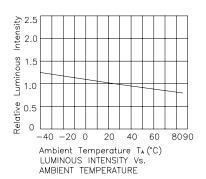


Super Bright Green KPCA03-102







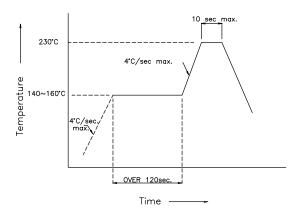


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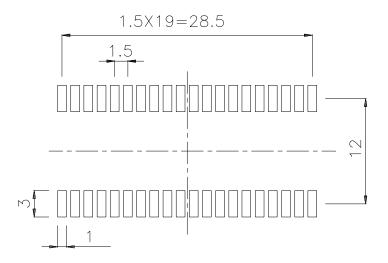


KPCA03-102 SMT Reflow Soldering Instruction

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.

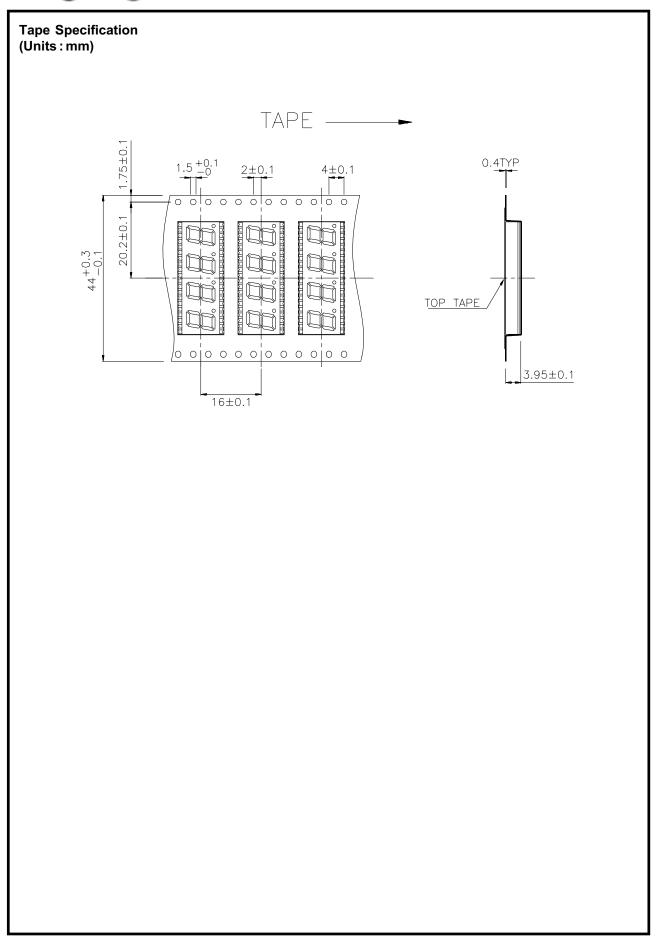


Recommended Soldering Pattern (Units:mm)



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